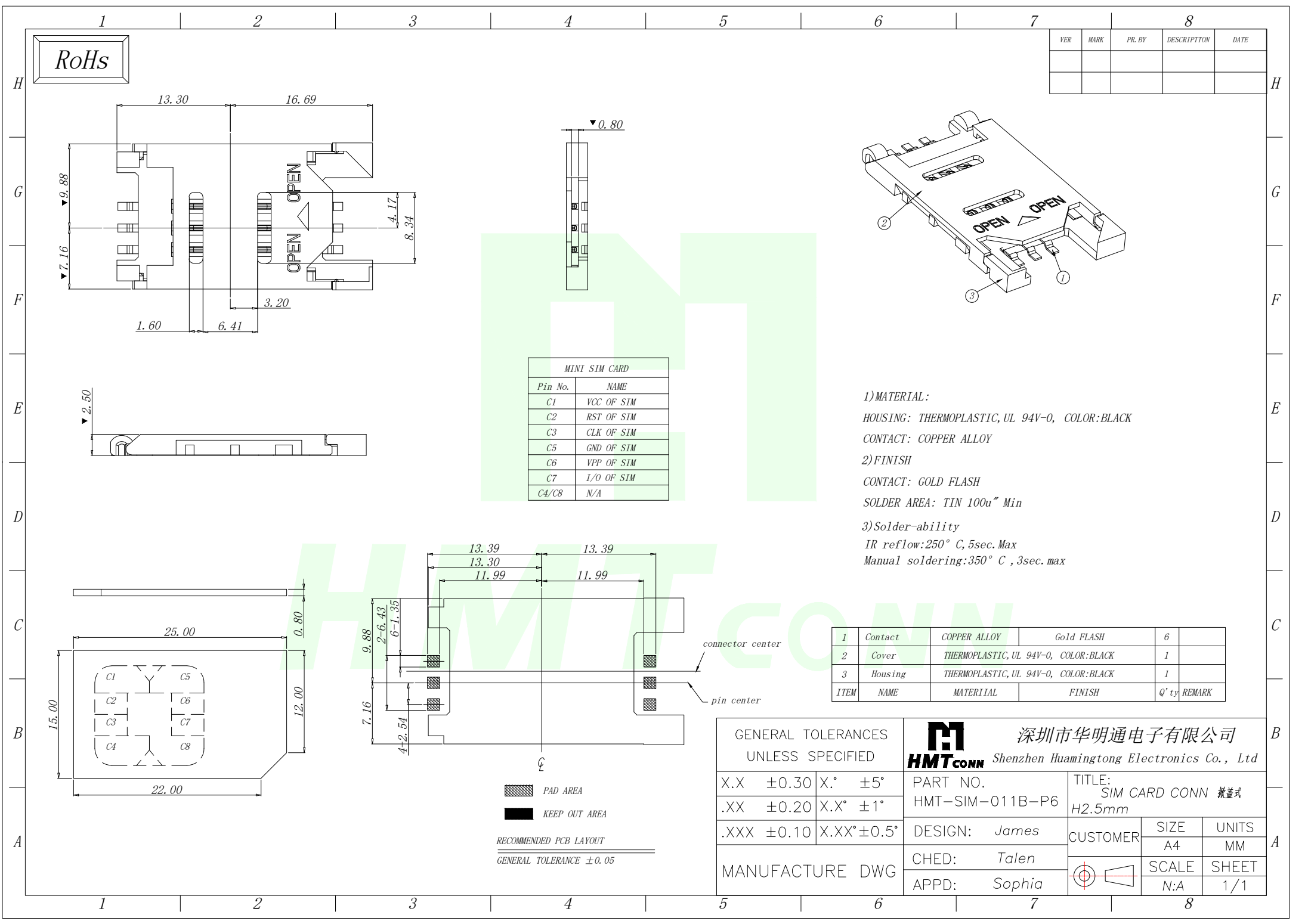




MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

1)MATERIAL:
HOUSING: THERMOPLASTIC,UL 94V-0, COLOR:BLACK
CONTACT: COPPER ALLOY

2)FINISH
CONTACT: GOLD FLASH
SOLDER AREA: TIN 100u" Min

3)Solder-ability
IR reflow:250° C,5sec.Max
Manual soldering:350° C ,3sec.max

1	Contact	COPPER ALLOY	Gold FLASH	6	
2	Cover	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
3	Housing	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
ITEM	NAME	MATERIAL	FINISH	Q'ty	REMARK

GENERAL TOLERANCES UNLESS SPECIFIED							
--	--	--	--	--	--	--	--

